

Features

Applications: transmission, TDM networks, SDH, SONET, wireless communications, IEEE 1588v2, SyncE, STRATUM III, wireless backhaul, metro carrier Ethernet, femtocells, picocells

Holdover stability: ± 0.37 ppm over 24 h

Overall stability: ± 4.60 ppm including 20 years aging

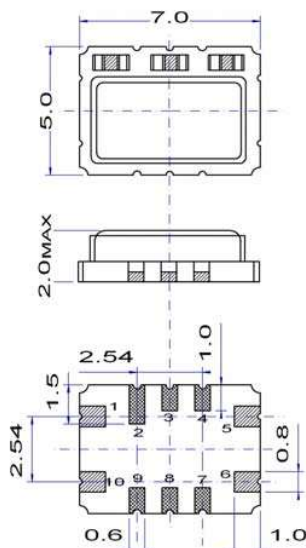
Output signal: CMOS

Specification

Parameter	Specification	
Frequency range	9.83040 ~ 32.0 MHz	
Standard frequencies	10.0, 12.80, 16.3840, 19.440, 20.0, 25.0, 26.0 & 32.0 MHz	
Frequency stability:	$\leq \pm 4.60$ ppm	overall stability including 20 years aging
vs. temperature	$\leq \pm 0.28$ ppm	-40 ~ +85 °C
vs. aging	$\leq \pm 3.0$ ppm	20 years
Holdover stability ⁽¹⁾	$\leq \pm 0.37$ ppm	over 24 hours
Frequency tolerance ex. factory	$\leq \pm 0.50$ ppm	@ +25 °C
Supply voltage	+3.3 V or +5.0 V	± 5 %
Supply current	< 6 mA	
Output signal	CMOS	
Output load	15 pF	± 5 %
Tri-state function	pin #9 high or open pin #9 low	pin #6 → oscillation pin #6 → high impedance
Phase noise @ 12.8 MHz carrier frequency	-145 dBc/Hz	@ 10 kHz
Operating temperature range	0 ~ +70 °C -40 ~ +85 °C	indoor use outdoor use
Storage temperature range	-55 ~ +125 °C	
Packaging units	tape & reel tape only	500 or 1'000 pieces < 500 pieces
Customer specifications on request		

⁽¹⁾ Including: frequency stability, vs temperature, supply change of ± 5 % and aging over 24 hours

Outline Dimensions & PIN Function & Solder Pattern



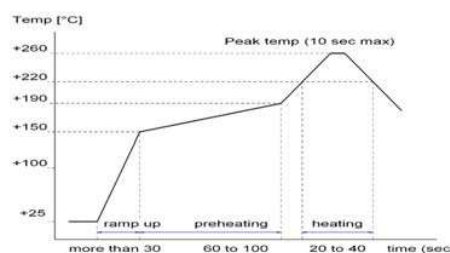
Pin function

- # 1 GND
- # 5 GND
- # 6 Output
- # 9 Tri-state
or not connected
- # 10 Vdc

Do not contact #2, #3, #4, #7 & #8

Do not design any conductive path between the pattern

Example for IR reflow soldering temperature



Example for soldering pattern

